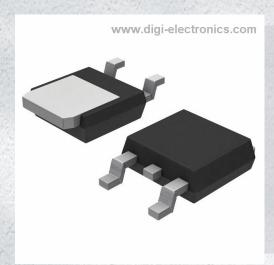


FDD9407L-F085 Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number FDD9407L-F085-DG

Manufacturer onsemi

Manufacturer Product Number FDD9407L-F085

Description MOSFET N-CH 40V 100A DPAK

Detailed Description N-Channel 40 V 100A (Tc) 227W (Tj) Surface Mount

TO-252AA



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RFQ Email: Info@DiGi-Electronics.com

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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
FDD9407L-F085	onsemi
Series:	Product Status:
PowerTrench®	Obsolete
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
40 V	100A (Tc)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
10V	2.4mOhm @ 80A, 4.5V
Vgs(th) (Max) @ ld:	Gate Charge (Qg) (Max) @ Vgs:
3V @ 250μA	125 nC @ 10 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±20V	6700 pF @ 25 V
FET Feature:	Power Dissipation (Max):
	227W (Tj)
Operating Temperature:	Grade:
-55°C ~ 175°C (TJ)	Automotive
Qualification:	Mounting Type:
AEC-Q101	Surface Mount
Supplier Device Package:	Package / Case:
TO-252AA	TO-252-3, DPAK (2 Leads + Tab), SC-63
Base Product Number:	
FDD9407	

Environmental & Export classification

8541.29.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	



ON Semiconductor®

FDD9407L-F085

N-Channel Logic Level PowerTrench $^{\circledR}$ MOSFET 40 V, 100 A, 1.7 m Ω

Features

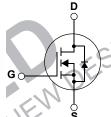
- Typical $R_{DS(on)}$ = 1.4 m Ω at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{q(tot)}$ = 96 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- PowerTrain Management
- Solenoid and Motor Drivers
- Integrated Starter/Alternator
- Primary Switch for 12V Systems







MOSFET Maximum Ratings T_J = 25°C unless otherwise noted.

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-to-Source Voltage	40	V
V_{GS}	Gate-to-Source Voltage	±20	V
	Drain Current - Continuous (V_{GS} =10) (Note 1) T_C = 25°C	100	Α
ID	Pulsed Drain Current T _C = 25°C	See Figure 4	^
E _{AS}	Single Pulse Avalanche Energy (Note 2)	128	mJ
D	Power Dissipation	227	W
P_{D}	Derate Above 25°C	1.52	W/°C
T _J , T _{STG}	Operating and Storage Temperature	-55 to + 175	οС
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.66	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient (Note 3)	52	°C/W

Notes:

- 1: Current is limited by bondwire configuration.
- 2: Starting T_J = 25°C, L = 40 μ H, I_{AS} = 80A, V_{DD} = 40V during inductor charging and V_{DD} = 0V during time in avalanche.
- 3: R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0,JC} is guaranteed by design, while R_{0,JA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD9407L	FDD9407L-F085	D-PAK(TO-252)	13"	16mm	2500units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted.

Parameter

Off Ch	aracteristics						
B _{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A$	V _{GS} = 0V	40	-	-	V
I _{DSS}	Drain-to-Source Leakage Current	V _{DS} =40V,	$T_{\rm J} = 25^{\rm o}{\rm C}$	-	-	1	μА
		$V_{GS} = 0V$	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	-	1	mA
I_{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

Test Conditions

Min.

On Characteristics

Symbol

Ī	V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$		1	1.8	3	V
Ī			$I_D = 80A, V_C$	_{SS} = 4.5V	-	1.9	2.4	$m\Omega$
	R _{DS(on)}		I _D = 80A,	$T_{J} = 25^{\circ}C$	-, (1.4	1.7	mΩ
			V _{GS} = 10V	$T_{.1} = 175^{\circ}C \text{ (Note 4)}$	-	2.4	2.9	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V = 25V V = 0V	6700	4 -	pF
C _{oss}	Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$	1640	-	pF
C _{rss}	Reverse Transfer Capacitance	10012	68	-	pF
R_g	Gate Resistance	$V_{GS} = 0.5V, f = 1MHz$	2.1	1	Ω
$Q_{g(ToT)}$	Total Gate Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DD} = 32V$	96	125	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 2V$ $I_D = 80A$	12	-	nC
Q_{gs}	Gate-to-Source Gate Charge	1 N 12 0	18	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge	NE OUT	15	-	nC

Switching Characteristics

t _{on}	Turn-On Time	-	-	68	ns
t _{d(on)}	Turn-On Delay	-	17	1	ns
t_r	Rise Time $V_{DD} = 20V$, $I_D = 80A$,	-	35	-	ns
t _{d(off)}	Rise Time V_{DD} = 20V, I_{D} = 80A, V_{GS} = 10V, R_{GEN} = 6 Ω	-	58	-	ns
t _f	Fall Time	-	21	-	ns
t _{off}	Turn-Off Time	-	-	104	ns

Drain-Source Diode Characteristics

V	Source-to-Drain Diode Voltage	$I_{SD} = 80A, V_{GS} = 0V$	-	-	1.25	V
V _{SD} Source-to-Drain Diode Voltage	I_{SD} = 40A, V_{GS} = 0V	-	-	1.2	V	
t _{rr}	Reverse-Recovery Time	$V_{DD} = 32V, I_F = 80A,$	-	82	107	ns
Q _{rr}	Reverse-Recovery Charge	dl _{SD} /dt = 100A/μs	-	106	138	nC

Note:

4: The maximum value is specified by design at $T_J = 175$ °C. Product is not tested to this condition in production.

Typical Characteristics

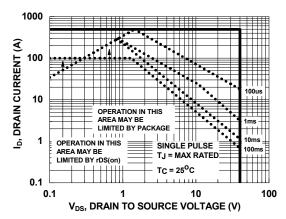
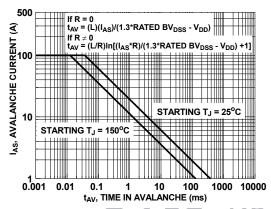


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

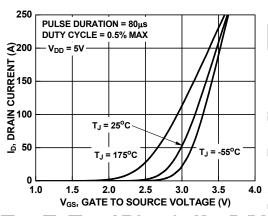


Figure 7. Transfer Characteristics

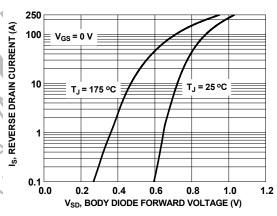


Figure 8. Forward Diode Characteristics

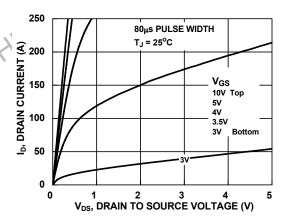


Figure 9. Saturation Characteristics

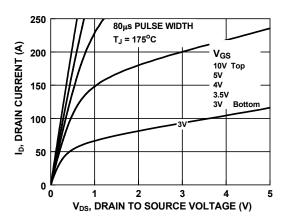


Figure 10. Saturation Characteristics

FDD9407L-F085 N-Channel Logic Level PowerTrench $^{f @}$ MOSFET

Typical Characteristics

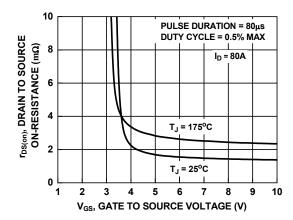


Figure 11. R_{DSON} vs. Gate Voltage

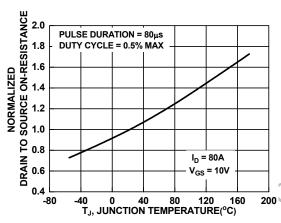


Figure 12. Normalized R_{DSON} vs. Junction Temperature

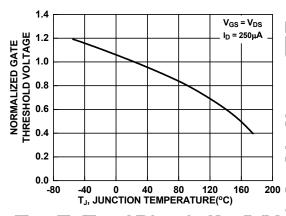


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

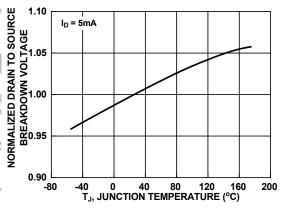


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

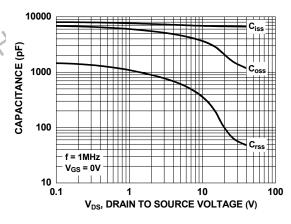


Figure 15. Capacitance vs. Drain to Source Voltage

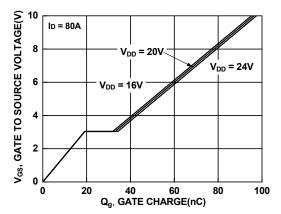


Figure 16. Gate Charge vs. Gate to Source Voltage



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